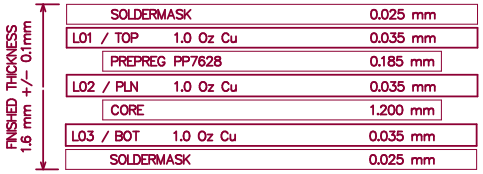
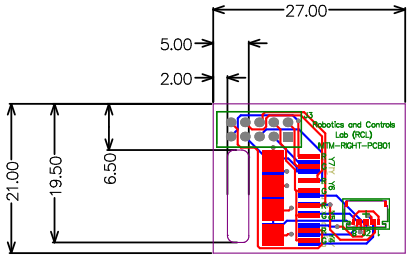
NOTES:

1. Performance and qualification per latest revisions of IPC-6011 and 6012: Class 2.
2. Acceptance per latest revisions of IPC-A-600 and IPC-A-610: Class 2.
3. Finished assembly to comply with latest amendments to EU Directive 2011/65/EU (RoHS2).
4. Flame Class: UL 94V-0
5. Flammability rating and manufacturer's UL file number to be marked on bottom silkscreen.
6. Dimensions are in mm unless specified otherwise. Tolerances are as indicated on Dimensions layer unless otherwise noted.
7. All dimensional limits apply after plating or processing.
8. Refer to drill table for hole size tolerances.
9. Hole / slot plating to be 0.001" minimum average and 0.0008" absolute minimum.
   Hole / slot diameters are specified after plating.
10. Board thickness and tolerance are as indicated on Layer Stack detail.
11. Remove all sharp edges and burrs 0.003" maximum.
12. Base Material: As noted in layer stack.
13. Soldermask: Liquid Photo Imageable in accordance with IPC-SM-840 (latest revision).
    Finish to be green and glossy. Registration to be within +/- 0.003 of respective outer circuit layers.
14. Silkscreen: White non-conductive ink (top and bottom). No ink to appear on exposed copper.
15. Finish: Electroless Nickel Immersion Gold (ENIG). Finish both sides with 150 micro inches minimum electroless Nickel (Ni) followed by minimum 2 microinches immersion Gold (Au).
16. Electrical Test: Perform 100% continuity and isolation testing per current IPC test methods.
17. Controlled impedance is not required.
18. Coordinate panelization with contract manufacturer.



LAYER STACK DETAIL
NOT TO SCALE



Tolerances unless otherwise specified:
.X +/- 0.20
.XX +/- 0.10
.XXX +/- 0.05

Robotics and Controls Laboratory (RCL) 3090 Kaiser Building 2332 Main Mall Vancouver, BC V6J 1R6	ENGINEER: Amir H. Hadi 2020.08.12 PCB DESIGNER: Amir H. Hadi 2020.08.12 DATE: 8/17/2020 FILE NAME: IMTM-Right-PCB01.PcbDoc	TITLE: Instrumented MTM BRKOUT Board PART NO.: IMTM-RIGHT-PCB01 DWG NO: IMTM-RIGHT-PCB01	REV: A SCALE: 1:1

Board Stack Report